Applicant: Manoocher Birang, et

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Version with markings to show changes made

In the claims:

Claims 37-53 have been added as follows:

A polishing pad for a chemical mechanical polishing apparatus, comprising: 37. an article having a polishing surface;

an aperture formed in the article; and

a substantially transparent plug secured in the aperture, wherein the plug includes a first section with a first lateral dimension and a second section with a second, different lateral dimension.

- The polishing pad of claim 27, wherein the first section of the plug is closer to the 38. polishing surface.
- The polishing pad of claim 33, wherein the first lateral dimension is smaller than 39. the second lateral dimension.
- The polishing pad of claim 37, wherein article includes a polishing layer with the 40. polishing surface and a backing layer.
- The polishing pad of claim 40, wherein the aperture includes a first portion in the 41. polishing layer and a second portion in the backing layer, and the first and second portions have different cross-sectional dimensions.
- The polishing pad of claim 41, wherein the first section of the plug is positioned 42. in the first section of the aperture and the second portion of the plug is positioned in the second section of the aperture.

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43. The polishing pad of claim 37, wherein article includes a polishing layer having an underside, the first section of the plug is positioned in the aperture, and the second section of the plug the underside of the polishing layer.

- 44. The polishing pad of claim 43, wherein the second section of the plug is secured to the underside of the polishing layer.
- 45. The polishing pad of claim 44, wherein the second section of the plug is adhesively attached to the underside of the polishing layer.
- 46. The polishing pad of claim 37, wherein a top surface of the plug is substantially coplanar with the polishing surface.
 - 47. A polishing pad for a chemical mechanical polishing apparatus, comprising: a polishing layer having a polishing surface and a bottom surface; an aperture formed in the polishing layer; and

a substantially transparent plug, wherein the plug includes a first section in the aperture and a second section secured to the bottom surface of the polishing layer.

- 48. The polishing pad of claim 47, wherein the first section of the plug has a first lateral dimension and the second section of the plug has a second, different lateral dimension.
- 49. The polishing pad of claim 48, wherein the first lateral dimension is smaller than the second lateral dimension.
- 50. The polishing pad of claim 47, wherein the second section of the plug is adhesively attached to the bottom surface of the polishing layer.
 - 51. The polishing pad of claim 47, further comprising a backing layer.

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52. The polishing pad of claim 51, wherein the backing layer includes an aperture aligned with the transparent plug.

53. The polishing pad of claim 47, wherein a top surface of the transparent section is substantially coplanar with the polishing surface.